

SOM-COM-HPC-A-TGL-UP3

COM-HPC® Client module Size A with the 11th Gen Intel® Core™ and Celeron® (Codename: Tiger Lake-UP3) Processors

11th Generation Intel® Core™ and Celeron® Processors in brand-new COM-HPC® format



HIGHLIGHTS



11th Gen Intel® Core™ processors and Intel® Celeron® processors



CONNECTIVITY

4x USB 4.0 / USB 3.2; 4x USB 2.0; 8x PCI-e x1 Gen3 ; 1x PCI-e x4 Gen4; up to 2x 2.5GbE



GRAPHICS

Intel® Iris Xe Graphics Core Gen12 GPU with up to 96 EU, up to 4 independent displays



MEMOR

Two DDR4 SO-DIMM Slots supporting DDR4-3200 ECC Memory











(1) Available in Industrial Temperature Range







MAIN FIELDS OF APPLICATION















Coffee & Vending

Medical

Up to 4x Display Port over Type-C (Alternate mode)

Transportation

Industrial Automation

Smart Devices Digital Signage

Energy & Utilities

FEATURES

FEATUR	KES			
	Processor	Ilth Generation Intel® Core™ and Celeron® Processors, also available in industrial temperature range Intel® Core™ i7-1185G7E, Quad Core @ 2.8GHz (4.4GHz in Turbo Boost) with HT, 12MB Cache, 28/15/12W cTDP Intel® Core™ i5-1145G7E, Quad Core @ 2.6GHz (4.1GHz in Turbo Boost) with HT, 8MB Cache, 28/15/12W cTDP Intel® Core™ i3-1115G4E, Dual Core @ 3.0GHz (3.9GHz in Turbo Boost) with HT, 6MB Cache, 28/15/12W cTDP Intel® Celeron® 6305E, Dual Core @ 1.8GHz, 4MB Cache, 15W TDP Intel® Core™ i7-1185GRE, Quad Core @ 2.8GHz (4.4GHz in Turbo Boost) with HT, 12MB Cache, with IBECC, 28/15/12W cTDP – Industrial (w/ Turbo OFF) Intel® Core™ i5-1145GRE, Quad Core @ 2.6GHz (4.1GHz in Turbo Boost) with HT, 8MB Cache, with IBECC, 28/15/12W cTDP – Industrial (w/ Turbo OFF) Intel® Core™ i3-1115GRE, Dual Core @ 3.0GHz (3.9GHz in Turbo Boost) with HT, 6MB Cache, 28/15/12W cTDP – Industrial (w/ Turbo OFF)	□ Video Resolution	DP, eDP: Up to 5120x3200 @60Hz 24bpp / 7680x4320@60Hz 30bpp with DSC MIPI-DSI: Up to 3200x2000 @60Hz 24 bpp, 5120x3200 @60Hz 24bpp with DSC HDMI® 1.4: Up to 4Kx2K 24-30Hz 24bpp / 4Kx2K 48-60Hz 12bpc (need dedicated redriver on carrier board)
■ P			Mass Storage	2 x S-ATA Gen3 Channels PCI-e x4 port can be used to connect, on the carrier board, M.2 NVMe drives
			로 Networking	Up to 2x NBase-T Ethernet interfaces, supporting 2.5Gb Ethernet connection, managed by as many Intel® i225 2.5GbE Controllers M.2 1216 SD Module supporting WiFi 802.1labgn+ac R2 MIMO 2x2 + MU-MIMO and BT 5.0
			•<- USB	Up to 4 x USB 4.0 / USB 3.2 Host ports 4 x USB 2.0 Host port
~	Max Cores	4 2x DDR4-3200 SODIMM Slots with IBECC (In-Band Error	PCI-e	1x PCI-e x4 Gen 4 port Up to 8x PCI-e Gen 3 lanes, groupable to support up to 4 root ports (5 root ports without the second 2.5GbE
Memory Memory		Correction Code), up to 64GB supported	=	controller)
	Graphics	Integrated Iris Xe Graphics Core Gen12 architecture, with up to 96 Execution Units MPEG2, WMV9, AVC/H.264, JPEG/MJPEG, HEVC/H.265, VP9, AV1 HW decoding, up to 8k @60. AVC/H.264, HEVC/H.265, JPEG, VP9 HW encoding Support up to 4 independent displays.	Audio	SoundWire and I2S Audio Interface
i G			Serial Ports	2 x UARTs
			Other Interfaces	2x 4-lane CSI-2 interfaces, optional SPI, SM Bus, 2x I2C, Watchdog timer, Carrier board FAN Control
	/ideo nterfaces	1x eDP 1.4b or MIPI_DSI 1.3 Up to 3x DP++ interface, supporting Display Port 1.4a and HDMI® 2.0b List at XP Display Port aver Type C (Alternate mode)		Management signals, ACPI signals, Safety Status signals Deep Sleep / Battery support Optional TPM 2.0 module on-board



SOM-COM-HPC-A-TGL-UP3

COM-HPC® Client module Size A with the 11th Gen Intel® Core™ and Celeron® (Codename: Tiger Lake-UP3) Processors

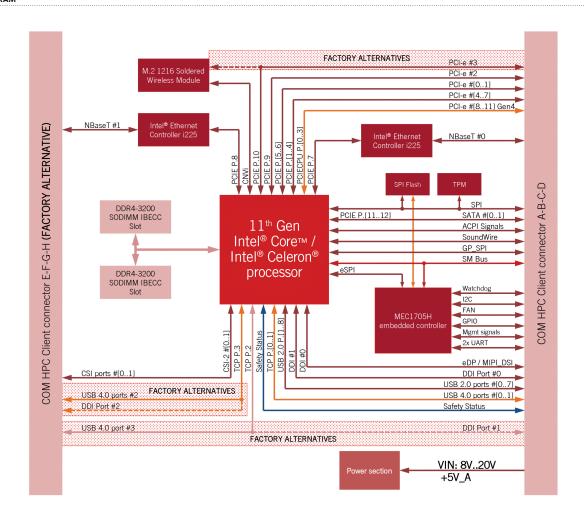
FEATURES

		Power Supply	$+8V_{\rm DC}$ $+20V_{\rm DC}$ Main power supply $+5V$ stand-by		
os	os	Operating System	Windows 10 IoT Enterprise LTSC Linux Kernel LTS Yocto VxWorks 7.0 Android		
		Operating Temperature*	0°C ÷ +60°C (Commercial version) -40°C ÷ +85°C (Industrial version)		

Dimensions 120 x 95 mm (COM-HPC® Size A Form factor, Client pinout)

*Measured at any point of SECO standard heatspreader for this product, during any and all times (including start-up). Actual temperature will widely depend on application, enclosure and/or environment. Upon customer to consider application-specific cooling solutions for the final system to keep the heatspreader temperature in the range indicated.

BLOCK DIAGRAM





Streamline and expedite your edge computing implementations

EDGEHOG OS

A flexible operating system that adapts to your needs, thanks to the customization tool and Docker support. Reliability and security are built-in through a dual-partition system and native integration with Exein's robust Al-based protection.

DATA ORCHESTRATION

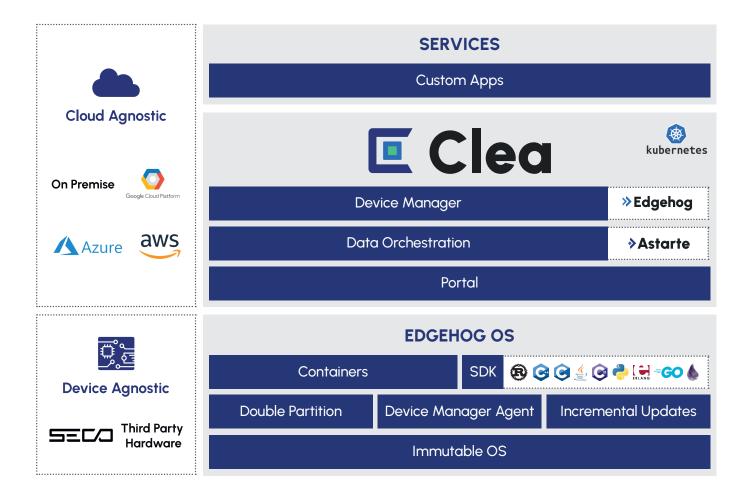
Integrate third-party services, simplify data flows and analysis, and enhance business efficiency by enabling easy and fast utilization of AI.

DEVICE MANAGER

Update, configure, and manage remote devices. Optimize time and costs to maximize operational efficiency and security without the need for costly field interventions.

PORTAL

Analyze data from remote devices, customize the user experience with applications tailored to user needs, and manage user rights, company access, and tenant privileges.



Scan to know more about our solution

EDGEHOG OS



CLEA DOCS



